



3D Optical Inspection of Complex Surfaces for Micromachined Parts and Products

Guest Editors:

Dr. Young-Sik Ghim

Prof. Dr. Young-Jin Kim

Prof. Dr. Ir. Sylvie Castagne

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Message from the Guest Editors

Dear Colleagues,

The manufacturing process for micromachined parts and products becomes more complicated and sophisticated in order to meet diverse customer needs as well as respond to the rapid changes in the emerging technological trends. To ensure high-quality of products by preventing any defects in manufacturing, precision inspection is essential. So, the growth of precision manufacturing has driven the advancement of related measurement technologies. As an example, in semiconductor industry, the development of 3D packaging technology emerged in the past decades has led to a new paradigm for manufacturing process by providing a volumetric packaging solution for higher integration and performance. This special issue will focus on the advances in 3D optical inspection techniques of complex surfaces for micromachined parts and products used in widespread applications ranging over, but limited to semiconductor, display, automotive, aerospace, and clean energy. Also, the challenges and technical limitations of measurement techniques facing the current industry are welcomed.

Dr. Young-Sik Ghim
Prof. Dr. Young-Jin Kim
Prof. Dr. Sylvie Castagne
Guest Editors





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Editor-in-Chief

Prof. Dr. Ai-Qun Liu

1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

Message from the Editor-in-Chief

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Micromachines Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

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